



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cohen, et al. Customer No: 32107
Assignee: Microfabrica Inc. Docket No: P-US024-A-MF
Title: Method for Electrochemically Forming Structures Including Non-Parallel Mating of Contact Masks and Substrates
Application No: 10/724,515 Filing Date: November 26, 2003
Examiner: Culbert, Roberts P. Group Art No: 1763

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

November 9, 2006

TRANSMITTAL FOR AMENDMENT & TERMINAL DISCLAIMER

Dear Sir:

Please find enclosed herewith the following items:

1. Return Postcard
2. Amendment Letter (3 pages)
 - a. Appendix A - Replacement Specification (31 pages)
 - b. Appendix B - Annotated Specification (31 pages)
3. Terminal Disclaimer (1 page)

Respectfully submitted,

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I certify that this paper and any indicated enclosure(s) and fee(s) are being deposited on November 9, 2006 with the U.S. Postal Service as first class or priority mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313.

Elizabeth Brown